

Claims

- [c1] 1. A microwave absorbing device in the form of a solid body and made of a composite material comprising a non-conductive matrix wherein conductive particles are dispersed, the conductive particles having a volume resistivity greater than about 2 ohms-cm.
- [c2] 2. The microwave absorbing device of claim 1 wherein the conductive particles are non-magnetic.
- [c3] 3. The microwave absorbing device of claim 1 wherein the volume resistivity of the conductive particles are less than about 2 megohms-cm.
- [c4] 4. The microwave absorbing device of claim 1 wherein the conductive particles are non-magnetic and the volume resistivity of the conductive particles are less than about 2 megohms-cm.
- [c5] 5. A composite material comprising a non-conductive matrix wherein conductive particles are dispersed, the conductive particles having a volume resistivity greater than about 2 ohms-cm.
- [c6] 6. The composite material of claim 5 wherein the con-

ductive particles are non-magnetic.

- [c7] 7. The composite material of claim 5 wherein the volume resistivity of the conductive particles are less than about 2 megohms·cm.
- [c8] 8. The composite material of claim 7 wherein the conductive particles are non-magnetic and the volume resistivity of the conductive particles are less than about 2 megohms·cm.
- [c9] 9. The composite material of claim 7 wherein some or all of the conductive particles are of a material from the group consisting of a semiconductor, a polymer, and carbon black.
- [c10] 10. The composite material of claim 7 wherein some or all of the conductive particles are conductive polymer particles.
- [c11] 11. The composite material of claim 7 wherein some or all of the conductive particles are of a material from the group consisting of silicon, germanium, a gallium compound, and an indium compound.